

09:42427

ABSTRACT

A semiconductor packaging structure for packaging a semiconductor element comprises: a flat substrate having a chip seat and having a plurality of outer lead wires for electrically connecting the packaging element and the liner. A wall is formed by molding compound and is installed at periphery of the substrate in order to prevent the problem of mold flush in packaging. Bonding wires are connected on the element for electrically connecting the packaging element with outer circuits. The liner extending inwards and outwards than the wall with a predetermined distance to prevent that a mold flush problem will induce in the wall. Therefore, in the present invention, a wall is formed by molding compound for reducing cost and increasing the flexibility in utility.